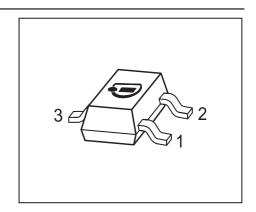


Silicon N-Channel MOSFET Triode

- For high-frequency stages up to 300 MHz preferably in FM applications
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101





ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration					Package	
BF999	LBs	1=G	2=D	3=S	-	1	1	SOT23

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	20	V
Continuous drain current	I _D	30	mA
Gate-source peak current	± I _{GSM}	10	mA
Total power dissipation	P _{tot}	200	mW
T _S ≤ 76 °C			
Storage temperature	$T_{ m stg}$	-55 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point ²⁾	R _{thchs}	≤ 370	K/W

¹Pb-containing package may be available upon special request

 $^{^{2}}$ For calculation of R_{thJA} please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics			•		•
Drain-source breakdown voltage	V _{(BR)DS}	20	-	-	V
$I_{\rm D} = 10 \ \mu {\rm A}, -V_{\rm GS} = 4 \ {\rm V}$					
Gate-source breakdown voltage	±V _{(BR)GSS}	6.5	-	12	
$\pm I_{GS} = 10 \text{ mA}, \ V_{DS} = 0$					
Gate-source leakage current	± I _{GSS}	-	-	50	nA
$\pm V_{GS} = 5 \text{ V}, \ V_{DS} = 0$					
Drain current	I _{DSS}	5	10	16	mA
$V_{DS} = 10 \text{ V}, \ V_{GS} = 0$					
Gate-source pinch-off voltage	-V _{GS(p)}	-	0.8	1.5	V
$V_{\rm DS} = 10 \text{ V}, I_{\rm D} = 20 \mu\text{A}$	- (1 /				

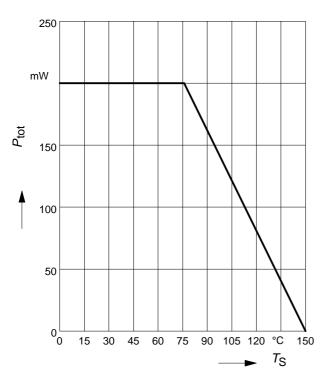
Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics	,	,		•	
Forward transconductance	g_{fs}	14	20	-	mS
$V_{\rm DS} = 10 \text{ V}, I_{\rm D} = 10 \text{ mA}$					
Gate input capacitance	$C_{ m gss}$	-	2.5	-	pF
$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, f = 10 \text{ MHz}$					
Output capacitance	$C_{\sf dss}$	-	0.9	-	pF
$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, f = 10 \text{ MHz}$					
Power gain	G_{p}	-	27	-	dB
$V_{\rm DS}$ = 10 V, $I_{\rm D}$ = 10 mA, f = 45 MHz					
Noise figure	F	-	2.1	-	dB
$V_{DS} = 10 \text{ V}, I_{D} = 10 \text{ mA}, f = 45 \text{ MHz}$					



Total power dissipation $P_{tot} = f(T_S)$

Output characteristics $I_D = f(V_{DS})$



18
mA

0.3V

14

12

0.1V

0.1V

0.1V

-0.1V

-0.4V

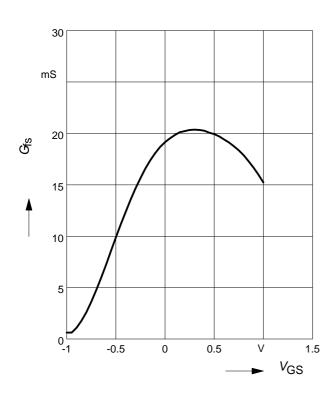
2

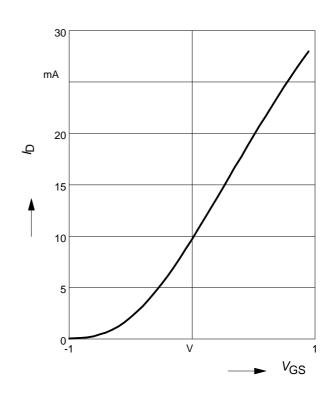
0

5
10
V
DS

Gate transconductance $g_{fS} = f(V_{GS})$

Drain current $I_D = (V_{GS})$

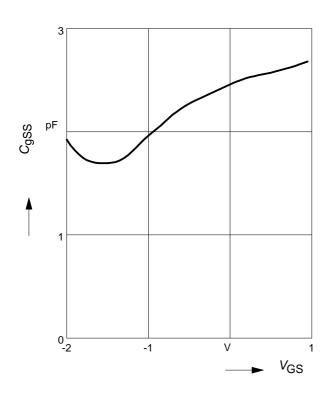


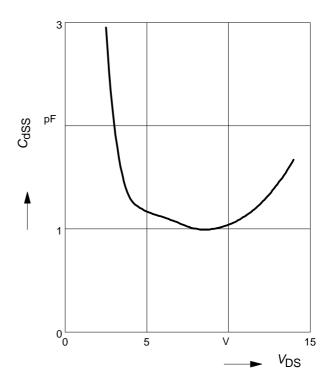




Gate input capacitance $C_{gss} = f(V_{GS})$

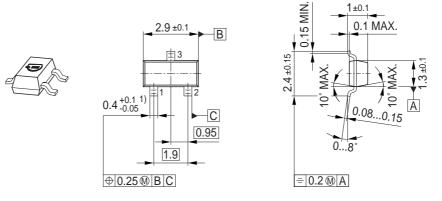
Output capacitance $C_{dss} = f(V_{DS})$





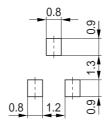


Package Outline

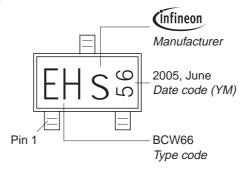


1) Lead width can be 0.6 max. in dambar area

Foot Print

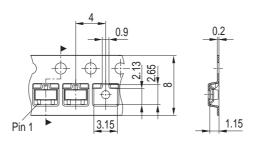


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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